

ENGLISH ABSTRACT FOR TW-311269

1 / 1 WPAT - •The Thomson Corp. - image

Accession Nbr :

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Sec. Acc. Non-CPI :

N1996-349084

Title :

Light-emitting diode or photodiode semiconductor component with light-permeable plastic packaging - has un-metallised portions of surface covered with micro-teeth for contacting encapsulant, which has been sprayed on, compressed and hardened

Derwent Classes :

U11 U12

Patent Assignee :

(SIEI) SIEMENS AG

Inventor(s) :

BRUNNER H

Nbr of Patents :

7

Nbr of Countries :

11

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EP-732740 A2 19960918 DW1996-42 H01L-023/29 Ger 6p *

AP: 1996EP-0103346 19960304

DSR: DE FI FR GB IE IT SE

DE19509262 A1 19960919 DW1996-43 H01L-023/28 4p

AP: 1995DE-1009262 19950315

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AP: 1996JP-0083046 19960313

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CN1138216 A 19961218 DW1998-06 H01L-023/28

AP: 1996CN-0108017 19960315

US5742098 A 19980421 DW1998-23 H01L-023/04 4p

AP: 1996US-0616319 19960315

DE19509262 C2 20011129 DW2001-73 H01L-023/28

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H01L-023/04 H01L-023/28 H01L-023/29 H01L-021/56 H01L-023/31 H01L-033/00 H05K-005/00

Abstract :

EP-732740 A

The semiconductor body (2), located on one connecting finger (1) of a system carrier, has metallic contacts (3,4) on its underside and top side, formed e.g. of Aluminium or alloy or other non-noble metal. The un-metallised surface areas are etched or otherwise treated to produce micro-teeth (5) for better contact with a transport block (8) of e.g. epoxy resin which covers the semiconductor body and metallic

contacts, the gold wire bond (6) and parts of the connecting fingers (1,7).

USE/ADVANTAGE - For light-emitting diodes and photodetector chips.

Adhesion between semiconductor body and plastic encapsulant is improved without recourse to thermal expansion coefft. matching, surface plasma activation or interlaying. (Dwg.1/1)

Manual Codes :

EPI: U11-D01A1 U12-A01A4 U12-A02B3

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1996-42

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Update Equivalents (Monthly) :

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